



Shenzhen Flourish Electronics Co., LTD

(C) D- C



SPECIFICATION FOR APPROVAL

PHOTOGRAPHY

PHOTOGRAPHY



Shenzhen Flourish Electronics Co., LTD

(C) D- C

Features

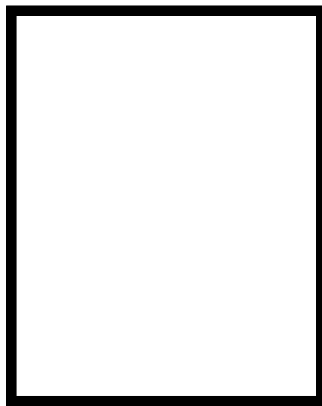
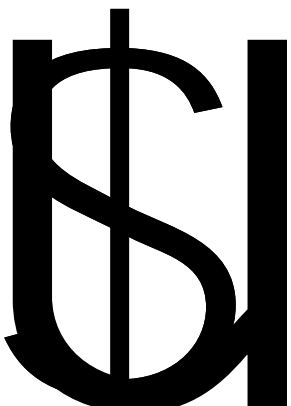


Test Condition



Shenzhen Flourish Electronics Co., LTD

(C) D- C





Shenzhen Flourish Electronics Co., LTD

(C) D- C

(Specification details & dimensions)

| | | | | | | | | |
|--|--|--|--|-------|--|--|--|--|
| | | | | | | | | |
| | | | | μ | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |



Shenzhen Flourish Electronics Co., LTD

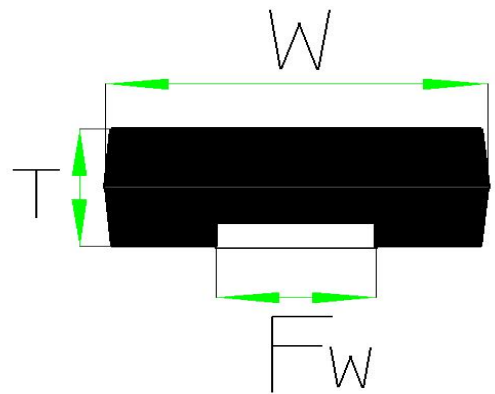
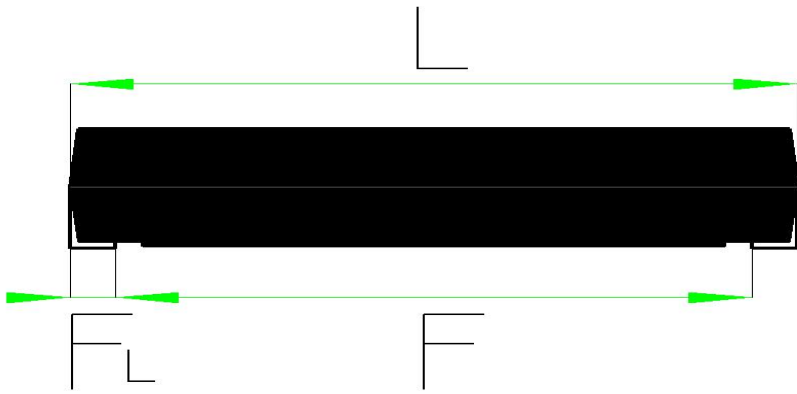
(C) D- C

| | | | | | | | | |
|--|--|--|--|--|--|--|--|--|
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |
| | | | | | | | | |

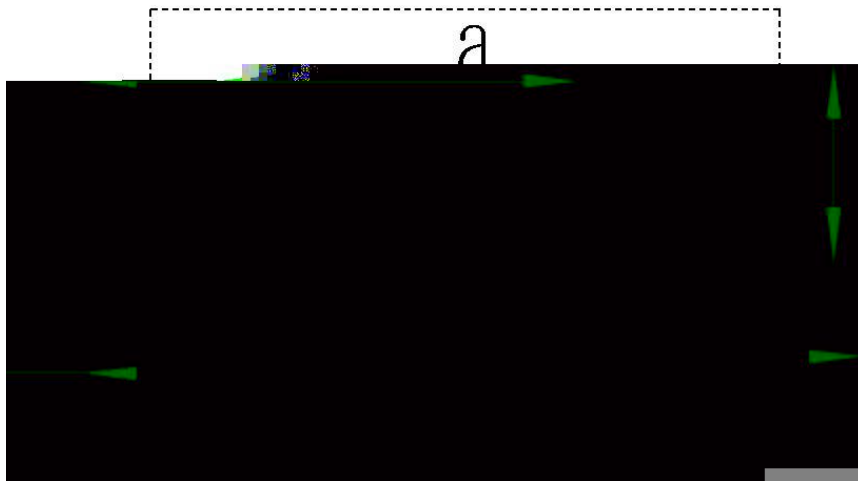


Shenzhen F ouri sh El ectroni cs Co. , LTD

(C) D- C



| | | | | | | |
|--|---|---|---|---|---|---|
| | | | | | | |
| | ± | ± | ± | ± | ± | ± |



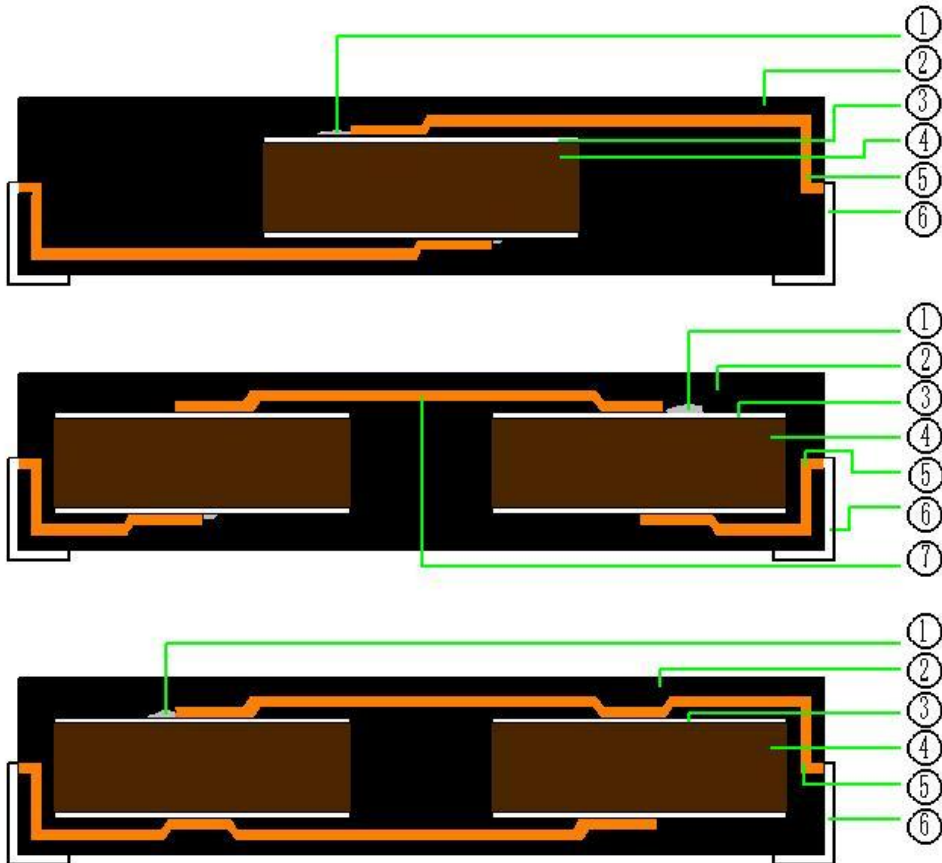
| | | | |
|--|--|--|--|
| | | | |
| | | | |

(Marking Explain)

Safety Certification:

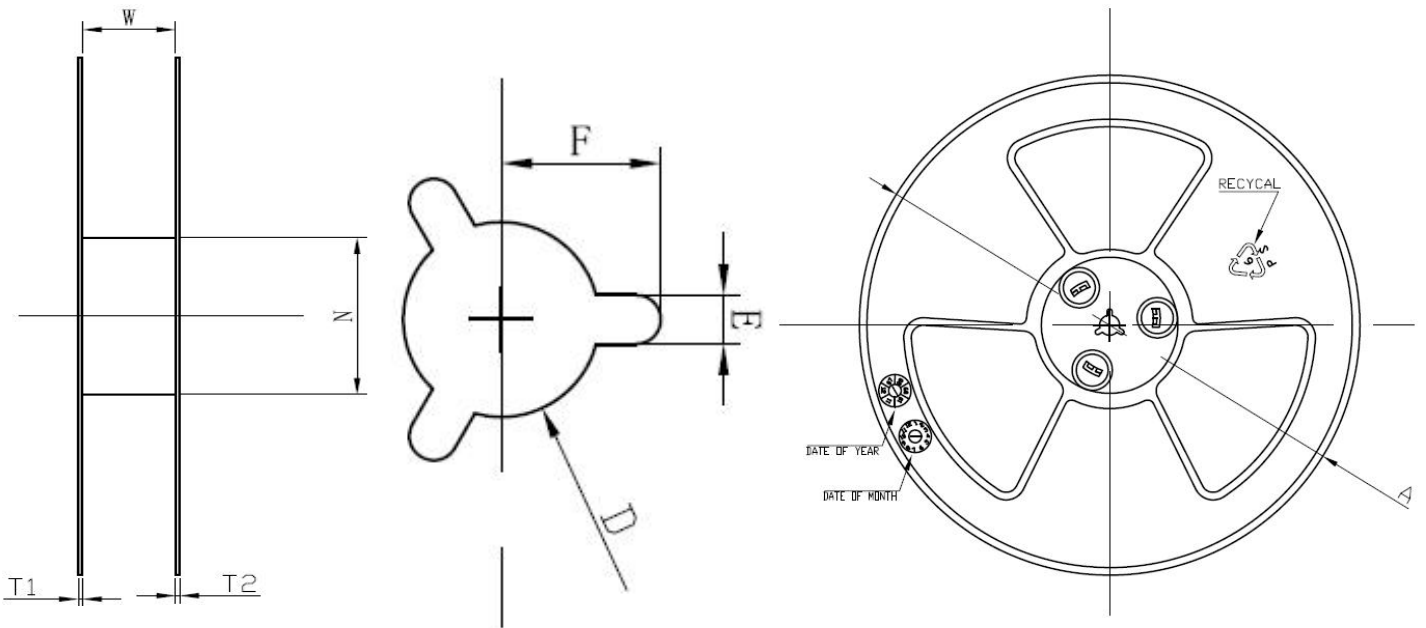
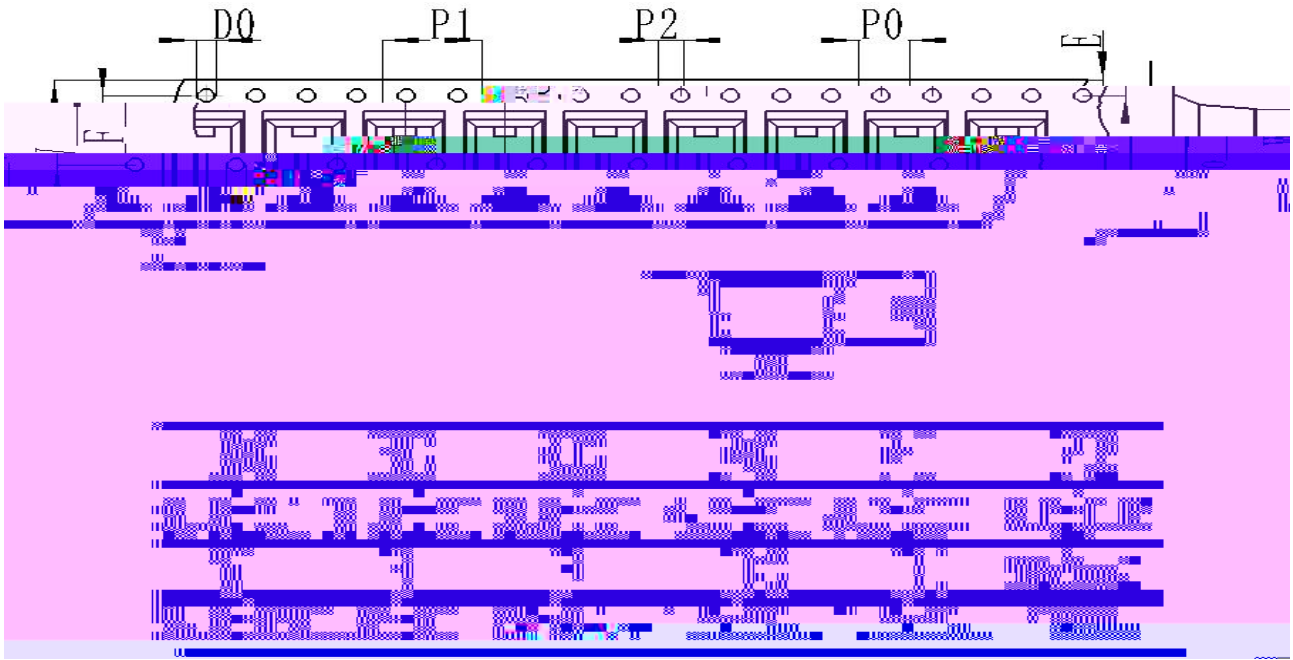


Structure

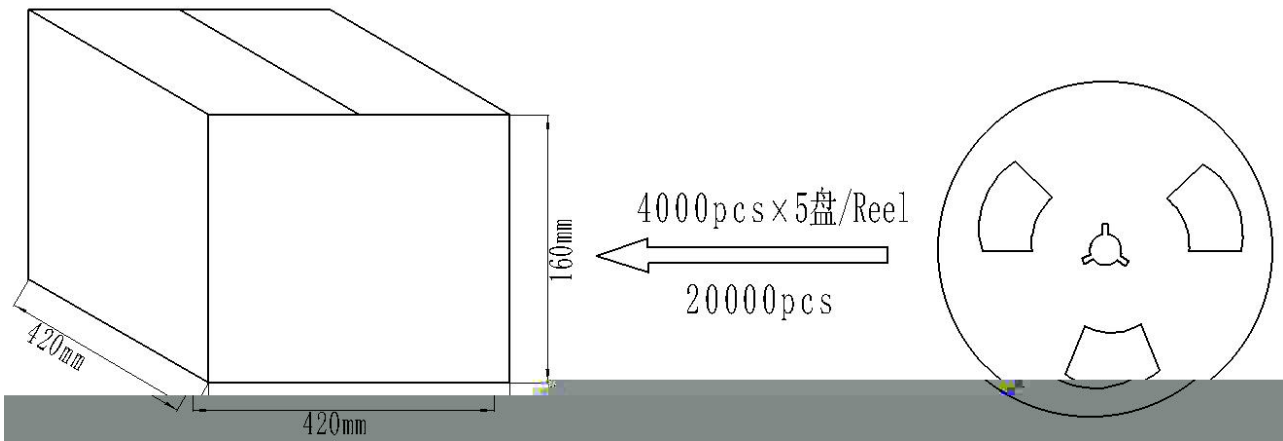


packing description

6.1



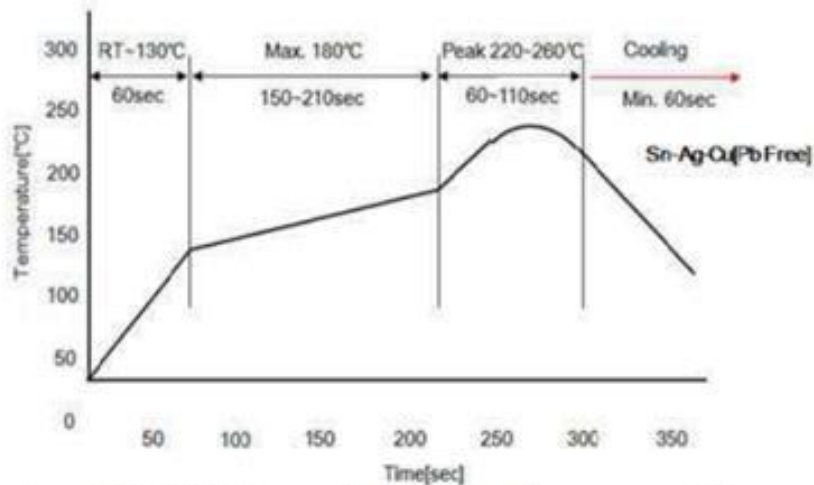
| | | | | | | | | |
|--|---|---|---|---|---|---|---|---|
| | | | | | | | | |
| | ± | ± | ± | ± | ± | ± | ± | ± |



Welding according to the instruction

7.1

☆ 回流焊接曲线



| 温区 | 温度范围 (°C) | 时间 (sec) | 备注 |
|----|------------------|----------|--------------------------------|
| a | RT~130 | 60 | 焊锡: Sn-Ag-Cu 高温时间: < 10 sec |
| b | 180 max | 150~210 | |
| c | 220~260(260 max) | 60~110 | |
| d | 220~RT | 60 min | |

当焊接温度低于锡的熔点时，贴片镀锡端子的可焊性将下降。使用之前请确认贴片镀锡电极的可焊性
焊接区出风口及内部空间最高温度不能超过 280°C，温度超过时，会造成产品发生失效。由于超温使用所造成的不良，我司不予承担责任。



Shenzhen Flourish Electronics Co., LTD

(C) D- C

7.2.

!

! ()

| Level | Bake@40C 5%RH | |
|-------|---------------------|--------------------------------------|
| | Saturated@30C/85%RH | At limit of Floor life+72hr@30C/60RH |
| 3 | 79days | 67days |

!

!



Shenzhen Flourish Electronics Co., LTD

(C) D- C

7.4

!

()